



INTERFLUX®
ELECTRONICS

DP 5600

SnBiAg solder paste



Interflux® DP 5600 is a no-clean solder paste for low temperature SnBiAg alloys.



Low melting temperature solder paste



Low voiding



Absolutely halogen free



High stability on the stencil

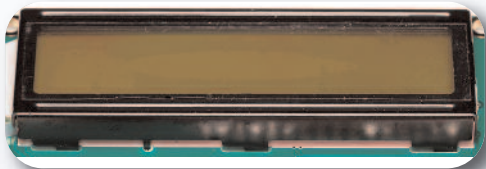


Suitable for dispensing



The acceptance of the SnBiAg alloy has strongly evolved in the electronics manufacturing market.

Where initially the alloy was mainly used for soldering consumer electronics and mechanical parts like shieldings, now it has found its way into fields like automation, medical, power electronics,...

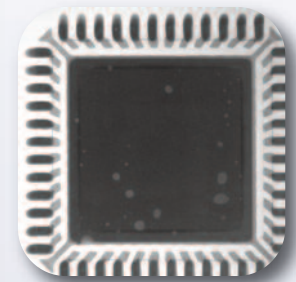


Despite its limitations, the alloy appears to have sufficient mechanical strength for many applications.

The advantage of the lower process temperature does not only consist of a saving in energy cost but also of a drastical reduction of the thermal impact on the electronic unit.

The DP 5600 soldering chemistry overcomes the challenges that the SnBiAg alloy brings in terms of solderability and stability.

The solder paste provides clean soldering results without the typical black spots combined with low voiding and high stability on the stencil.



Sn42Bi57Ag1 : ~139°C



Type 3 and Type 4



Jars, cartridges and syringes

www.interflux.com

